

Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from, Europe, America and south Asia, supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of "Quality Parts, Customers Priority, Honest Operation, and Considerate Service", our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip, ALPS, ROHM, Xilinx, Pulse, ON, Everlight and Freescale. Main products comprise IC, Modules, Potentiometer, IC Socket, Relay, Connector. Our parts cover such applications as commercial, industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!



## Contact us

Tel: +86-755-8981 8866 Fax: +86-755-8427 6832

Email & Skype: info@chipsmall.com Web: www.chipsmall.com

Address: A1208, Overseas Decoration Building, #122 Zhenhua RD., Futian, Shenzhen, China









## APT20M22LVR

200V 100A  $\mathbf{0.022}\Omega$ 

# POWER MOS V®

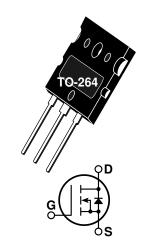
Power MOS V® is a new generation of high voltage N-Channel enhancement mode power MOSFETs. This new technology minimizes the JFET effect, increases packing density and reduces the on-resistance. Power MOS V® also achieves faster switching speeds through optimized gate layout...

Faster Switching

100% Avalanche Tested

Lower Leakage

Popular TO-264 Package



#### **MAXIMUM RATINGS**

All Ratings:  $T_C = 25^{\circ}C$  unless otherwise specified.

Symbol	Parameter	APT20M22LVR	UNIT	
V <sub>DSS</sub>	Drain-Source Voltage	200	Volts	
I <sub>D</sub>	Continuous Drain Current @ T <sub>C</sub> = 25°C <sup>(5)</sup>	100	Amna	
I <sub>DM</sub>	Pulsed Drain Current ① ⑤	400	Amps	
$V_{GS}$	Gate-Source Voltage Continuous	±30	Volts	
V <sub>GSM</sub>	Gate-Source Voltage Transient	±40	VOILS	
P <sub>D</sub>	Total Power Dissipation @ T <sub>C</sub> = 25°C	520	Watts	
, D	Linear Derating Factor	4.16	W/°C	
T <sub>J</sub> ,T <sub>STG</sub>	Operating and Storage Junction Temperature Range	-55 to 150	°C	
T <sub>L</sub>	Lead Temperature: 0.063" from Case for 10 Sec.	300	]	
I <sub>AR</sub>	Avalanche Current <sup>① ⑤</sup> (Repetitive and Non-Repetitive)	100	Amps	
E <sub>AR</sub>	Repetitive Avalanche Energy ①	50	mı	
E <sub>AS</sub>	Single Pulse Avalanche Energy <sup>④</sup>	2500	- mJ	

### STATIC ELECTRICAL CHARACTERISTICS

Symbol	Characteristic / Test Conditions	MIN	TYP	MAX	UNIT
BV <sub>DSS</sub>	Drain-Source Breakdown Voltage $(V_{GS} = 0V, I_D = 250\mu\text{A})$	200			Volts
I <sub>D(on)</sub>	On State Drain Current $^{\textcircled{2}}$ $^{\textcircled{5}}$ $(V_{DS} > I_{D(on)} \times R_{DS(on)} Max, V_{GS} = 10V)$	100			Amps
R <sub>DS(on)</sub>	Drain-Source On-State Resistance ② (V <sub>GS</sub> = 10V, 0.5 I <sub>D[Cont.]</sub> )			0.022	Ohms
I <sub>DSS</sub>	Zero Gate Voltage Drain Current $(V_{DS} = V_{DSS}, V_{GS} = 0V)$			25	μА
	Zero Gate Voltage Drain Current ( $V_{DS} = 0.8 V_{DSS}$ , $V_{GS} = 0V$ , $T_{C} = 125$ °C)			250	
I <sub>GSS</sub>	Gate-Source Leakage Current $(V_{GS} = \pm 30V, V_{DS} = 0V)$			±100	nA
V <sub>GS(th)</sub>	Gate Threshold Voltage $(V_{DS} = V_{GS}, I_{D} = 2.5 \text{mA})$	2		4	Volts

CAUTION: These Devices are Sensitive to Electrostatic Discharge. Proper Handling Procedures Should Be Followed.

APT Website - http://www.advancedpower.com

**USA** 405 S.W. Columbia Street Bend, Oregon 97702-1035 Phone: (541) 382-8028 FAX: (541) 388-0364 **EUROPE** 

Avenue J.F. Kennedy Bât B4 Parc Cadéra Nord

F-33700 Merignac - France

Phone: (33) 5 57 92 15 15

FAX: (33) 5 56 47 97 61

Symbol	Characteristic	Test Conditions	MIN	TYP	MAX	UNIT
C <sub>iss</sub>	Input Capacitance	$V_{GS} = 0V$		8500	10200	
C <sub>oss</sub>	Output Capacitance	V <sub>DS</sub> = 25V		1950	2730	pF
C <sub>rss</sub>	Reverse Transfer Capacitance	f = 1 MHz		560	840	
$Q_g$	Total Gate Charge <sup>③</sup>	V <sub>GS</sub> = 10V		290	435	
Q <sub>gs</sub>	Gate-Source Charge	$V_{DD} = 0.5 V_{DSS}$		66	100	nC
$Q_{gd}$	Gate-Drain ("Miller") Charge	$I_D = I_{D[Cont.]} @ 25^{\circ}C$		120	180	
t <sub>d(on)</sub>	Turn-on Delay Time	V <sub>GS</sub> = 15V		16	32	
t <sub>r</sub>	Rise Time	$V_{DD} = 0.5 V_{DSS}$		25	50	20
t <sub>d(off)</sub>	Turn-off Delay Time	$I_{D} = I_{D[Cont.]} @ 25^{\circ}C$		48	72	ns
t <sub>f</sub>	Fall Time	$R_{G} = 0.6\Omega$		5	10	

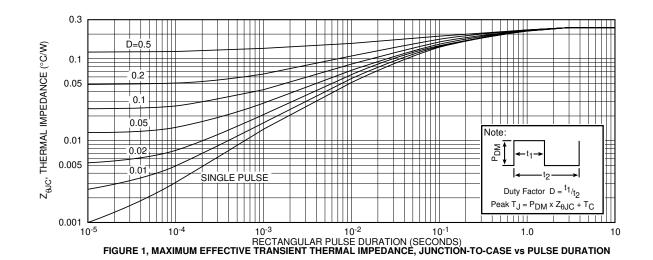
### **SOURCE-DRAIN DIODE RATINGS AND CHARACTERISTICS**

Symbol	Characteristic / Test Conditions	MIN	TYP	MAX	UNIT
I <sub>s</sub>	Continuous Source Current <sup>⑤</sup> (Body Diode)			100	Amno
I <sub>SM</sub>	Pulsed Source Current ① ⑤ (Body Diode)			400	Amps
V <sub>SD</sub>	Diode Forward Voltage ② $(V_{GS} = 0V, I_{S} = -I_{D[Cont.]})$			1.3	Volts
t <sub>rr</sub>	Reverse Recovery Time $(I_S = -I_{D[Cont.]}, dI_S/dt = 100A/\mu s)$		330		ns
Q <sub>rr</sub>	Reverse Recovery Charge $(I_S = -I_{D[Cont.]}, dI_S/dt = 100A/\mu s)$		5.8		μС

#### THERMAL CHARACTERISTICS

Symbol	Characteristic	MIN	TYP	MAX	UNIT
$R_{ hetaJC}$	Junction to Case			0.24	°C/W
$R_{\thetaJA}$	Junction to Ambient			40	

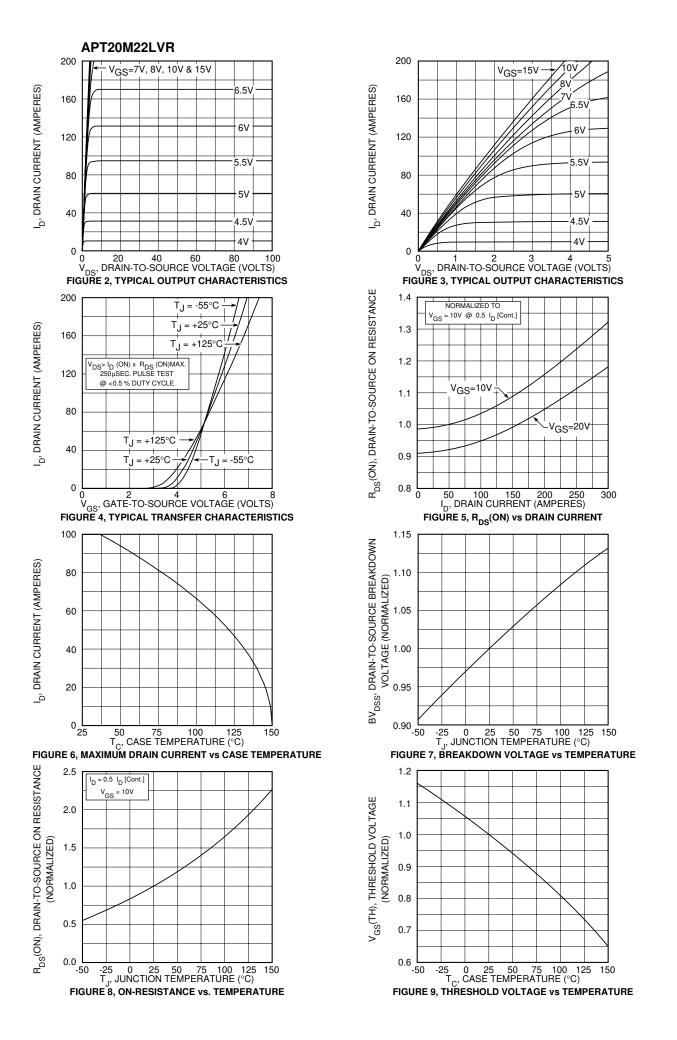
APT Reserves the right to change, without notice, the specifications and information contained herein.

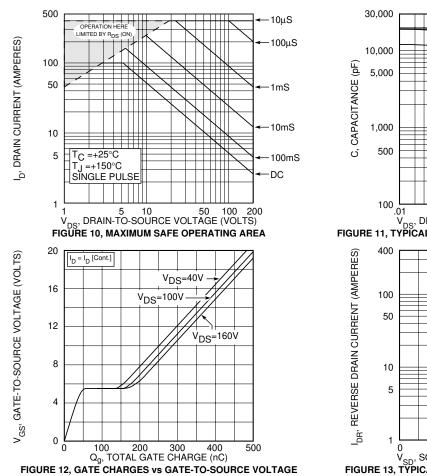


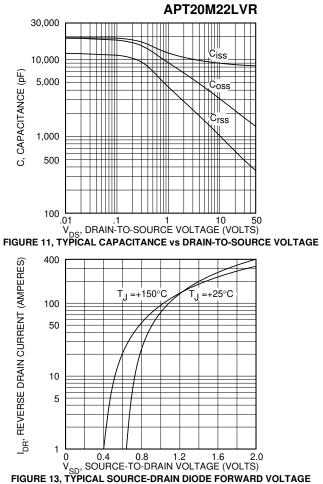
<sup>3</sup> See MIL-STD-750 Method 3471

 $<sup>\</sup>bigcirc$  Starting T<sub>i</sub> = +25°C, L = 500μH, R<sub>G</sub> = 25Ω, Peak I<sub>L</sub> = 100A

<sup>(5)</sup> The maximum current is limited by lead temperature.







#### **TO-264 Package Outline**

